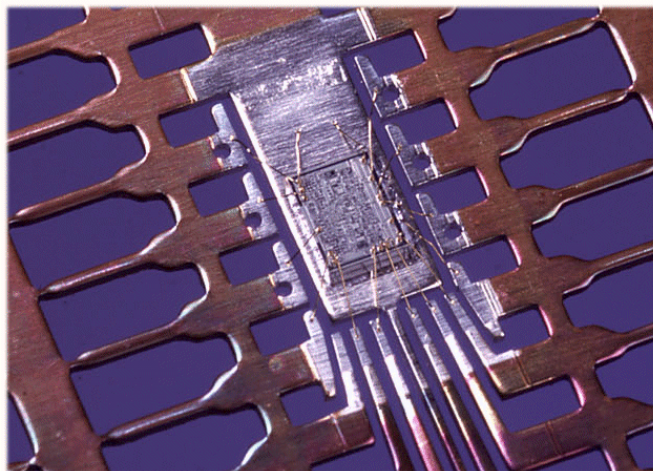


PACKAGE MATERIAL LIST

item #	material	thickness	thermal conductivity
leadframe	copper	0.25 mm	2.61 W/cm°C
die attach	epoxy glue (silver glue)	10-40 μm	0.01 W/cm°C
molding compound	epoxy resin	3 mm	0.0063W/cm°C

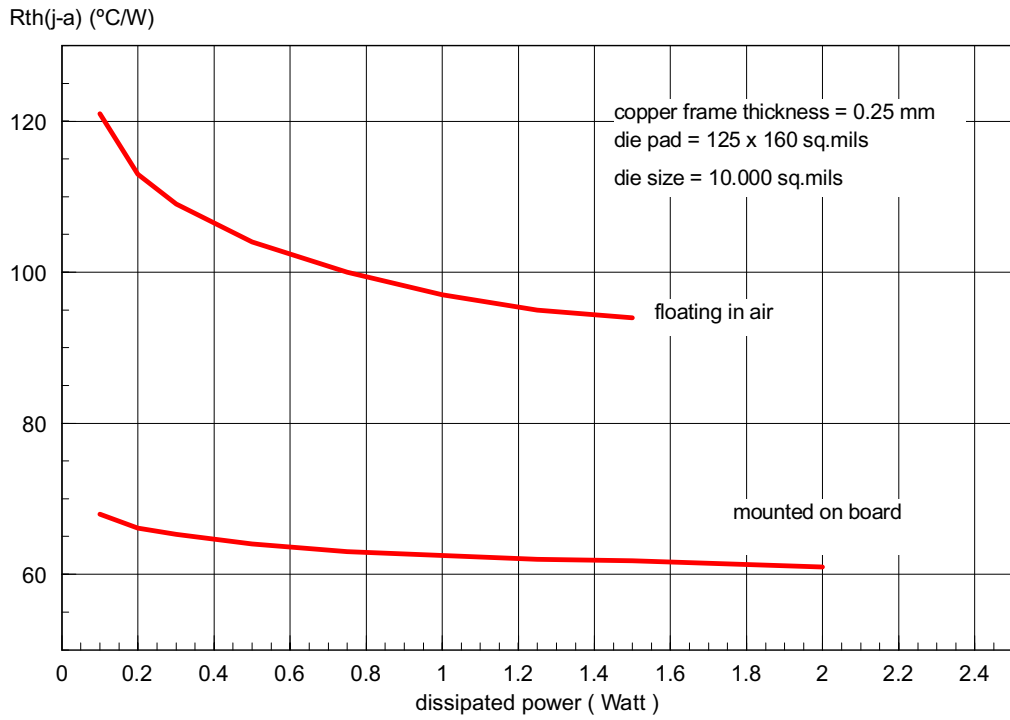
Typical assembly configuration before molding :



Charts enclosed :

- 1) Rth(j-a) vs power dissipation
- 2) Zth(j-a) vs time width and die size

1)



2)

